

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	60	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _{RM}		
Average Rectified Output Current	I _O	1	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	50	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Case (Note 5)	R _{θJC}	40	°C/W
Typical Thermal Resistance Junction to Ambient (Note 5)	R _{θJA}	110	
Typical Thermal Resistance Junction to Case (Note 6)	R _{θJC}	8	
Typical Thermal Resistance Junction to Ambient (Note 6)	R _{θJA}	75	
Typical Thermal Resistance Junction to Solder point (Note 6)	R _{θJS}	18	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	60	—	—	V	I _R = 1.0mA
Forward Voltage Drop	V _F	—	0.32	0.37	V	I _F = 0.1A, T _J = +25°C
		—	0.43	0.49		I _F = 0.7A, T _J = +25°C
		—	0.46	0.53		I _F = 1A, T _J = +25°C
Leakage Current (Note 7)	I _R	—	0.002	—	mA	V _R = 10V, T _J = +25°C
		—	0.010	0.060		V _R = 60V, T _J = +25°C
		—	0.40	—		V _R = 60V, T _J = +85°C
		—	3.7	—		V _R = 60V, T _J = +125°C
Total Capacitance	C _T	—	48	—	pF	V _R = 10V, f = 1MHz

Notes: 5. Device mounted on 1*MRP FR-4 PC board, 2oz.
6. Device mounted on 1-inch sq. copper pad, 2oz.
7. Short duration pulse test used to minimize self-heating effect.

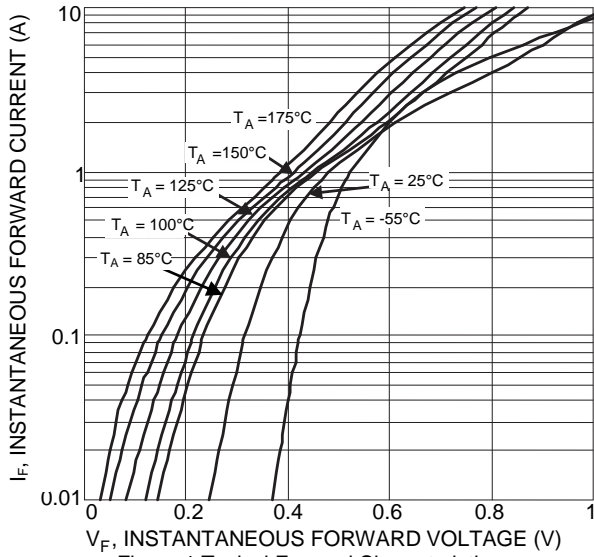


Figure 1 Typical Forward Characteristics

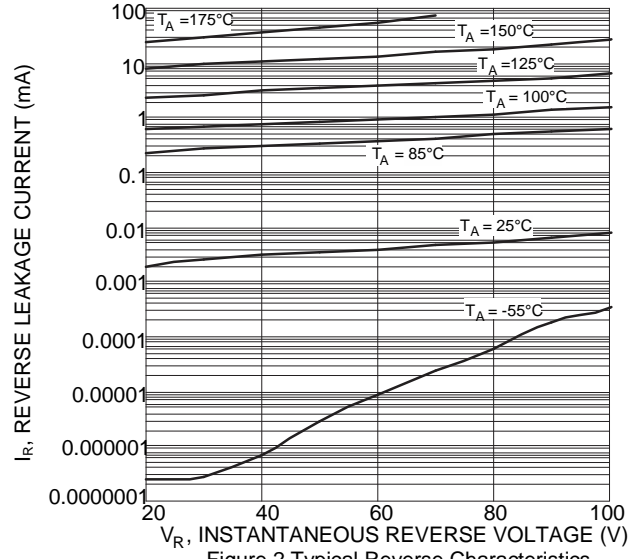


Figure 2 Typical Reverse Characteristics

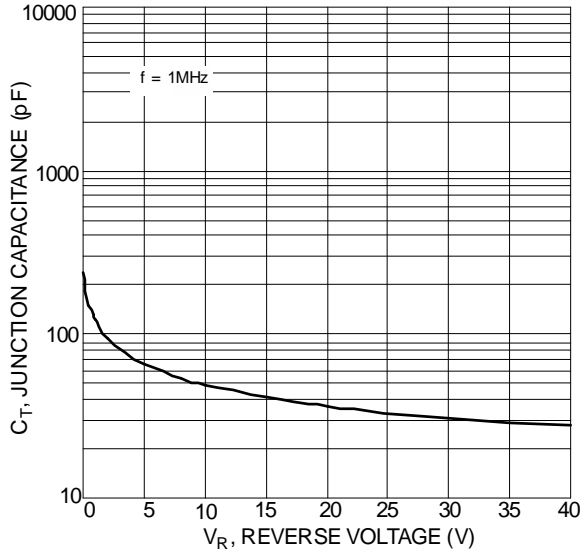


Figure 3 Typical Junction Capacitance

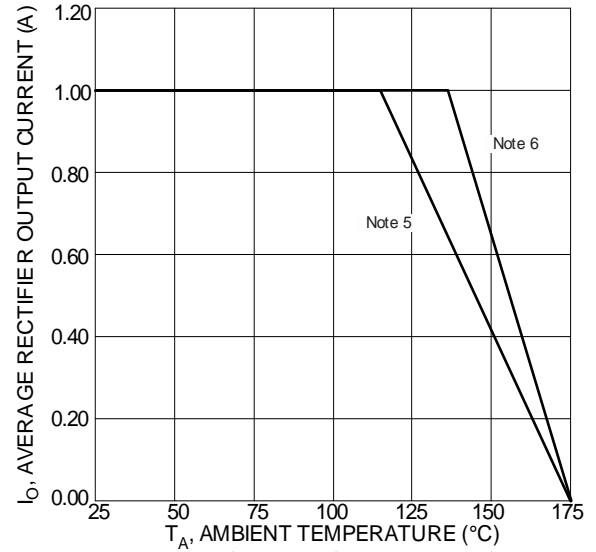


Figure 4 DC Forward Current Derating Curve

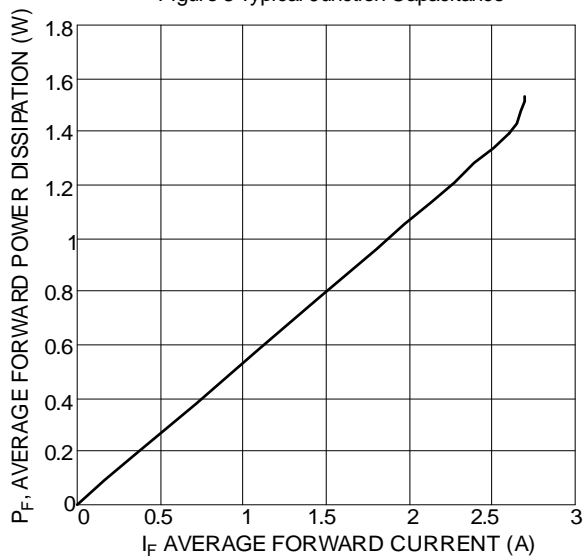
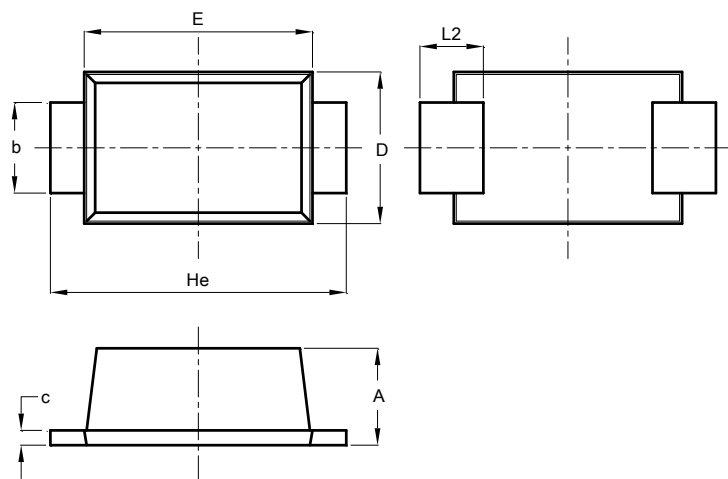


Figure 5 Forward Power Dissipation

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOD123F

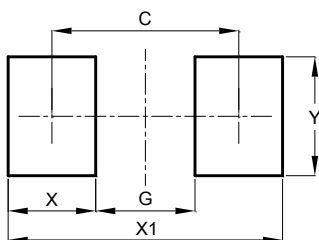


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Dim	Min	Max	Typ
A	0.81	1.15	-
b	0.80	1.35	-
c	0.05	0.30	-
D	1.70	1.90	1.80
E	2.60	2.80	2.70
He	3.30	3.70	3.50
L2	0.35	0.85	-
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

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Dimensions	Value (in mm)
C	2.86
G	1.52
X	1.34
X1	4.20
Y	1.80

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